PFR 150-Sun Sensor Baffle Chipping Title:

Assembly : Probe	**SubAssembly :** Sun Sensor	
Component : Baffle	**Units Affected:** 2 3 4 5 0	**Units fixed:** 0 0 0 0 0 0
Originator: Paul Turin		
Organization: SSL	**Date: 3/05/2006**	
Phone:510-642-5289	**Email :pturin@ssl.berkeley.edu**	

Failure Occurred During (Check one √)

□ Functional test □ Qualification test □ S/C Integration □ Launch operations X Other (Flight Assy)

Environment when failure occurred:

□ Ambient □ Vibration □ Shock □ Acoustic
□ Thermal □ Vacuum □ Thermal-Vacuum □ EMI/EMC

Problem Description

During incoming inspection it was noted that both sun sensor baffles had chips in the Z307 black paint applied to the scalloped baffle protrusions. IN addition, the painted edges were slightly polished in spots making them more reflective than the undisturbed paint. The chips expose reflective metal that could allow glint to enter the sun sensor.

Analyses Performed to Determine Cause

The baffles were shipped together from the vendor in a single bag, allowing the baffles to rub against each other and chip and polish the paint.

Corrective Action/ Resolution

Future shipments should include individual wrapping of the baffles with a nonabrasive paddingand separate bagging to prevent contact.

Acceptance:
MAM: Ron Jackson_____; MSE: Ellen Taylor_____

PM: Peter Harvey_____; Cognizant Engineer_____

Date of Closure_____